

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
KHAY CHWAN SAW	04/05/2019
CHAU FATT CHIANG	04/05/2019
STEFAN MACHEINER	04/08/2019
WAE CHET YONG	04/05/2019
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17412787
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ATTORNEY DOCKET NUMBER:	1012-3075/2018P52270 US01
NAME OF SUBMITTER:	JAMES M. O'NEILL
SIGNATURE:	/James M. O'Neill, Reg. #69,924/
DATE SIGNED:	08/26/2021
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 2	
source=1012-3075_Declaration_and_Assignment#page1.tif	

**DECLARATION AND ASSIGNMENT
FOR PATENT AND DESIGN APPLICATIONS**

UNITED STATES PATENT RIGHTS, OR
UNITED STATES PLUS ALL FOREIGN PATENT RIGHTS

Chip to Chip Interconnect in Encapsulant of Molded Semiconductor Package

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to the application attached hereto. If the application is not attached hereto, the application is as identified by the attorney docket number as set forth above and/or the following:

United States Application Number or PCT International Appln. No. 16/375,479

filed on Apr 4, 2019.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

WHEREAS, the undersigned has invented certain at least one claim in the application identified.

WHEREAS, Infineon Technologies AG

of Am Campeon 1-15 Neubiberg, Germany 85579

its heirs, successors, legal representatives and assigns (hereinafter designated as the Assignee) is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent(s) that may be granted therefor in the United States of America and

in any foreign countries.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned has (have) sold, assigned and transferred, and by these considerations does (do) sell, assign and transfer unto said Assignee the full and exclusive right to the said invention in the United States of America, its territories, dependencies and possessions and the entire right, title and interest in and to any and all Letters Patent(s) which may be granted therefor in the United States of America, its territories, dependencies and possessions, and if the box above is designated, in any and all foreign countries; and to any and all divisions, reissues, continuations, conversions and extensions of all of the above for the full term or terms for which the same may be granted.

The undersigned agrees to execute all papers necessary in connection with this application and any continuing, divisional, conversion or reissue applications thereof or any other proceedings before the United States Patent and Trademark Office and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agrees to execute all papers and documents and to perform any act which may be necessary in connection with claims or provisions of the International Convention for the Protection of Industrial Property or similar agreements.

The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of (a) valid United States of America patent(s) and any foreign patent(s) to the Assignee and to vest all rights therein hereby conveyed to said Assignee as fully and entirely as the same would have been held by the undersigned if this Assignment and sale had not been made.

The undersigned hereby authorizes and requests the Patent and Trademark Office Officials in the United States of America and in any foreign countries to issue any and all Letters Patent(s) resulting from said application or any continuing, divisional conversion or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has the full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grants the Assignee's legal representatives the power to insert, before or after this document has been executed by the undersigned, any information to identify the instant patent application which may be necessary or desirable in order to comply with the rules of the U.S. Patent and Trademark Office.

The undersigned hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

The undersigned hereby acknowledges that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

In witness whereof, executed by the undersigned on the date opposite the undersigned name.

Full Name of Inventor:

Khay Chwan Saw

5.4.2019

Saw

Date

Inventor Signature

Full Name of Inventor:

Chau Fatt Chiang

5.4.2019

Chiang

Date

Inventor Signature

Full Name of Inventor:

Stefan Macheiner

5.4.2019

Macheiner

Date

Inventor Signature

Full Name of Inventor:

Wae Chet Yong

5/4/19 (YONG WC)

Wae Chet Yong

Date

Inventor Signature